SECTION 10 ELECTRICAL AND THERMAL CHARACTERISTICS

This section provides information on the maximum rating and thermal characteristics for the MC68000, MC68HC000, MC68HC001, MC68EC000, MC68008, and MC68010.

10.1 MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	Vcc	-0.3 to 7.0	٧
Input Voltage	V _{in}	-0.3 to 7.0	٧
Maximum Operating Temperature Range Commerical Extended "C" Grade Commerical Extended "I" Grade	TA	T _L to T _H 0 to 70 –40 to 85 0 to 85	°C
Storage Temperature	T _{stg}	-55 to 150	°C

This device contains protective circuitry against damage due to high static voltages or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either GND or V_{CC}).

10.2 THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Symbol	Value	Rating
Thermal Resistance	θJA		θJC		°C/W
Ceramic, Type L/LC		30		15*	
Ceramic, Type R/RC	ŀ	33		15	
Plastic, Type P		30		15*	
Plastic, Type FN		45*		25*	

^{*}Estimated

10.3 POWER CONSIDERATIONS

The average die-junction temperature, TJ, in °C can be obtained from:

$$T_{J} = T_{A} + (P_{D} \cdot {}^{\theta}J_{A}) \tag{1}$$

where:

TA = Ambient Temperature, °C

⁶J_A = Package Thermal Resistance, Junction-to-Ambient, °C/W

PD = PINT + PI/O

PINT = ICC x VCC, Watts — Chip Internal Power

PI/O = Power Dissipation on Input and Output Pins — User Determined

For most applications, PI/O<PINT and can be neglected.

An appropriate relationship between PD and TJ (if PI/O is neglected) is:

$$PD = K \div (T_J + 273 \, ^{\circ}C)$$
 (2)

Solving Equations (1) and (2) for K gives:

$$K = PD \cdot (TA + 273^{\circ}C) + {\theta}JA \cdot PD^{2}$$
(3)

where K is a constant pertaining to the particular part. K can be determined from equation (3) by measuring PD (at thermal equilibrium) for a known TA. Using this value of K, the values of PD and TJ can be obtained by solving Equations (1) and (2) iteratively for any value of TA.

The curve shown in Figure 10-1 gives the graphic solution to the above equations for the specified power dissipation of 1.5 W over the ambient temperature range of -55 °C to 125 °C using a maximum ^θJA of 45 °C/W. Ambient temperature is that of the still air surrounding the device. Lower values of ^θJA cause the curve to shift downward slightly; for instance, for ^θJA of 40 °/W, the curve is just below 1.4 W at 25 °C.

The total thermal resistance of a package (${}^{\theta}JA$) can be separated into two components, ${}^{\theta}JC$ and ${}^{\theta}CA$, representing the barrier to heat flow from the semiconductor junction to the package (case) surface (${}^{\theta}JC$) and from the case to the outside ambient air (${}^{\theta}CA$). These terms are related by the equation:

$$^{\theta}JA = ^{\theta}JC + ^{\theta}CA \tag{4}$$

 6 JC is device related and cannot be influenced by the user. However, 6 CA is user dependent and can be minimized by such thermal management techniques as heat sinks, ambient air cooling, and thermal convection. Thus, good thermal management on the part of the user can significantly reduce 6 CA so that 6 JA approximately equals ; 6 JC. Substitution of 6 JC for 6 JA in equation 1 results in a lower semiconductor junction temperature.

Table 10-1 summarizes maximum power dissipation and average junction temperature for the curve drawn in Figure 10-1, using the minimum and maximum values of ambient temperature for different packages and substituting $^{\theta}$ JC for $^{\theta}$ JA (assuming good thermal management). Table 10-2 provides the maximum power dissipation and average junction temperature assuming that no thermal management is applied (i.e., still air).

NOTE

Since the power dissipation curve shown in Figure 10-1 is negatively sloped, power dissipation declines as ambient temperature increases. Therefore, maximum power dissipation occurs at the lowest rated ambient temperature, but the highest average junction temperature occurs at the maximum ambient temperature where power dissipation is lowest.

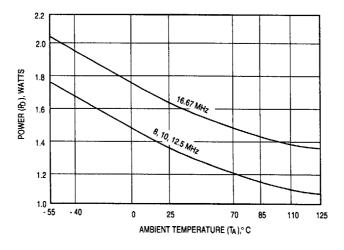


Figure 10-1. MC68000 Power Dissipation (PD) vs Ambient Temperature (TA) (Not Applicable to MC68HC000/68HC001/68EC000)

Table 10-1. Power Dissipation and Junction Temperature vs Temperature (θJC=θJA)

Package	T _A Range	θJC (°C/W)	P _D (W) @ T _A Min.	TJ (°C) @ T _A Min.	P _D (W) @ T _A Max.	TJ (°C) @ T _A Max.
L/LC	0°C to 70°C -40°C to 85°C 0°C to 85°C	15 15 15	1.5 1.7 1.5	23 -14 23	1.2 1.2 1.2	88 103 103
Р	0°C to 70°C	15	1.5	23	1.2	88
R/RC	0°C to 70°C -40°C to 85°C 0°C to 85°C	15 15 15	1.5 1.7 1.5	23 -14 23	1.2 1.2 1.2	88 103 103
FN	0°C to 70°C	25	1.5	38	1.2	101

NOTE: Table does not include values for the MC68000 12F.

Does not apply to the MC68HC000, MC68HC001, and MC68EC000.

Table 10-2. Power Dissipation and Junction Temperature vs Temperature (⁰JC≠⁰JC)

Package	T _A Range	θJA (°C/W)	P _D (W) @ T _A Min.	TJ (°C) @ T _A Min.	P _D (W) @ T _A Max.	T _J (°C) @ T _A Max.
L/LC	0°C to 70°C	30	1.5	23	1.2	88
	-40°C to 85°C	30	1.7	-14	1.2	103
	0°C to 85°C	30	1.5	23	1.2	103
Р	0°C to 70°C	30	1.5	23	1.2	88
R/RC	0°C to 70°C	33	1.5	23	1.2	88
	-40°C to 85°C	33	1.7	-14	1.2	103
	0°C to 85°C	33	1.5	23	1.2	103
FN	0°C to 70°C	40	1.5	38	1.2	101

NOTE: Table does not include values for the MC68000 12F.

Does not apply to the MC68HC000, MC68HC001, and MC68EC000.

Values for thermal resistance presented in this manual, unless estimated, were derived using the procedure described in Motorola Reliability Report 7843 "Thermal Resistance Measurement Method for MC68XXX Microcomponent Devices" and are provided for design purposes only. Thermal measurements are complex and dependent on procedure and setup. User-derived values for thermal resistance may differ.

10.4 CMOS CONSIDERATIONS

The MC68HC000, MC68HC001, and MC68EC000, with it significantly lower power consumption, has other considerations. The CMOS cell is basically composed of two complementary transistors (a P channel and an N channel), and only one transistor is turned on while the cell is in the steady state. The active P-channel transistor sources current when the output is a logic high and presents a high impedance when the output is logic low. Thus, the overall result is extremely low power consumption because no power

is lost through the active P-channel transistor. Also, since only one transistor is turned on during the steady state, power consumption is determined by leakage currents.

Because the basic CMOS cell is composed of two complementary transistors, a virtual semiconductor controlled rectifier (SCR) may be formed when an input exceeds the supply voltage. The SCR that is formed by this high input causes the device to become latched in a mode that may result in excessive current drain and eventual destruction of the device. Although the MC68HC000 and MC68EC000 is implemented with input protection diodes, care should be exercised to ensure that the maximum input voltage specification is not exceeded. Some systems may require that the CMOS circuitry be isolated from voltage transients; other may require additional circuitry.

The MC68HC000 and MC68EC000, implemented in CMOS, is applicable to designs to which the following considerations are relevant:

- 1. The MC68HC000 and MC68EC000 completely satisfies the input/output drive requirements of CMOS logic devices.
- The HCMOS MC68HC000 and MC68EC000 provides an order of magnitude reduction in power dissipation when compared to the HMOS MC68000. However, the MC68HC000 does not offer a "power-down" mode.

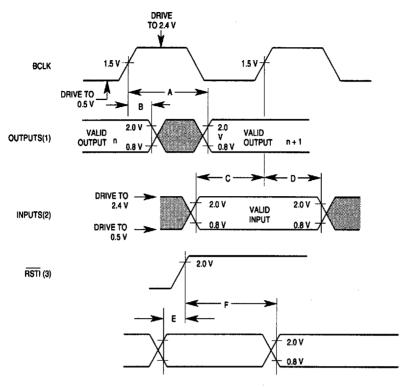
10.5 AC ELECTRICAL SPECIFICATION DEFINITIONS

The AC specifications presented consist of output delays, input setup and hold times, and signal skew times. All signals are specified relative to an appropriate edge of the clock and possibly to one or more other signals.

The measurement of the AC specifications is defined by the waveforms shown in Figure 10-2. To test the parameters guaranteed by Motorola, inputs must be driven to the voltage levels specified in the figure. Outputs are specified with minimum and/or maximum limits, as appropriate, and are measured as shown. Inputs are specified with minimum setup and hold times, and are measured as shown. Finally, the measurement for signal-to-signal specifications are shown.

NOTE

The testing levels used to verify conformance to the AC specifications does not affect the guaranteed DC operation of the device as specified in the DC electrical characteristics.



NOTES:

- 1. This output timing is applicable to all parameters specified relative to the rising edge of the clock.
- This input timing is applicable to all parameters specified relative to the rising edge of the clock.
 This timing is applicable to all parameters specified relative to the negation of the RESET signal.

- A. Maximum output delay specification.
- B. Minimum output hold time.
- C. Minimum input setup time specification.
- D. Minimum input hold time specification.
- E. Mode select setup time to RESET negated.
- F. Mode select hold time from RESET negated.

Figure 10-2. Drive Levels and Test Points for AC Specifications

10.6 MC68000/68008/68010 DC ELECTRICAL CHARACTERISTICS

(VCC=5.0 VDC±5%; GND=0 VDC; TA=TL TO TH)

Characteristic	Symbol	Min	Max	Unit
Input High Voltage	VIH	2.0	Vcc	V
Input Low Voltage	VIL	GND-0.3	0.8	V
Input Leakage Current BERR, BGACK, BR DTACK, CLK, IPLO—IPL2, VPA @ 5.25 V HALT, RESET	IN	_	2.5 20	μА
Three-State (Off State) Input Current AS, A1—A23, D0—D15, FC0—FC2, @ 2.4 V/0.4 V LDS, R/W, UDS, VMA	ITSI	_	20	μА
Output High Voltage (I_{OH} = -400 μ A) E* (I_{OH} = -400 μ A) A\$, A1-A23, B\$\bar{G}\$, D0-D15, FC0-FC2, L\$\bar{D}\$\$, R\$, W, UDS, VMA	Voн	V _{CC} -0.75	2.4	V
Output Low Voltage (IOL= 1.6 mA) HALT (IOL = 3.2 mA) A1—A23, BG, FC0-FC2 (IOL = 5.0 mA) RESET (IOL = 5.3 mA) E, AS, D0—D15, LDS, RW, UDS, VMA	VOL	_ 	0.5 0.5 0.5 0.5	٧
Power Dissipation (see POWER CONSIDERATIONS)	PD***	_	_	w
Capacitance (Vin=0 V, TA=25°C, Frequency=1 MHz)**	C _{in}	_	20.0	рF
Load Capacitance HALT All Others	CL	_	70 130	pF

^{*}With external pullup resistor of 1.1 Ω .

^{**}Capacitance is periodically sampled rather than 100% tested.

^{***}During normal operation, instantaneous VCC current requirements may be as high as 1.5 A.

10.7 DC ELECTRICAL CHARACTERISTICS (VCC=5.0 VDC±5%; GND=0 VDC; TA=TL

TO TH) (Applies To All Processors Except The MC68EC000)

Characteristic	Symbol	Min	Max	Unit
Input High Voltage	ViH	2.0	ن ک	٧
Input Low Voltage	VIL	GND-0.3	0.8	٧
Input Leakage Current BERR, BGACK, BR, DTACK, CLK, IPL0—IPL2, VPA @ 5.25 V MODE, HALT, RESET	IN	-	2.5 20	μΑ
Three-State (Off State) Input Current AS, A0—A23, D0—D15, @ 2.4 V/0.4 V FC0-FC2, LDS, R/W, UDS, VMA	ITSI	_	20	μА
Output High Voltage E, \overline{AS} , A0–A23, \overline{BG} , D0–D15, FC0–FC2, \overline{LDS} , $\overline{R/W}$, \overline{UDS} , \overline{VMA}	∨он	V _{CC} -0.75	ı	>
Output Low Voltage (IOL = 1.6 mA) HALT (IOL = 3.2 mA) A0—A23, BG, FC0-FC2 (IOL = 5.0 mA) RESET (IOL = 5.3 mA) E, AS, D0—D15, LDS, RW, UDS, VMA Current Dissipation* f = 8 MHz	VOL	- - - -	0.5 0.5 0.5 0.5	V mA
f = 10 MHz f = 12.5 MHz f = 16.67 MHz f = 20 MHz	טי		30 35 50 70	
Power Dissipation	PD	_	0.13 0.16 0.19 0.26 0.38	w
Capacitance (Vin = 0 V, TA=25°C, Frequency=1 MHz)**	C _{in}		20.0	ρF
Load Capacitance HALT All Others	CL	_	70 130	pF

^{*} Current listed are with no loading.

10.8 AC ELECTRICAL SPECIFICATIONS — CLOCK TIMING (See Figure 10-3)

(Applies To All Processors Except The MC68EC000)

Num	Characteristic	8 MHz*		z* 10 MHz*		12.5 MHz*		16.67 MHz 12F		16 MHz		20 MHZ**		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
	Frequency of Operation	4.0	8.0	4.0	10.0	4.0	12.5	8.0	16.7	8.0	16.7	8.0	20.0	MHz
1	Cycle Time	125	250	100	250	80	250	60	125	60	125	50	125	ns
2,3	Clock Pulse Width (Measured from 1.5 V to 1.5 V for 12F)	55 55	125 125	45 45	125 125	35 35	125 125	27 27	62.5 62.5	27 27	62.5 62.5	21 21	62.5 62.5	ns
4,5	Clock Rise and Fall Times	_	10 10	_	10 10	_	5 5	_	5 5	_	5 5	1	4 4	ns

^{*}These specifications represent an improvement over previously published specifications for the 8-, 10-, and 12.5-MHz MC68000 and are valid only for product bearing date codes of 8827 and later.

M68000 8-/16-/32-BIT MICROPROCESSORS USER'S MANUAL



^{**} Capacitance is periodically sampled rather than 100% tested.

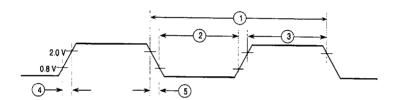
^{**}This frequency applies only to MC68HC000 and MC68EC000 parts.

10.9 MC68008 AC ELECTRICAL SPECIFICATIONS — CLOCK TIMING (See

Figure 10-3)

Num	Characteristic	8 N	lHz*	10 1	/Hz*	Unit
		Min	Max	Min	Max	
	Frequency of Operation	2.0	8.0	2.0	10.0	MHz
1	Cycle Time	125	500	100	500	ns
2,3	Clock Pulse Width	55	250	45	250	ns
4,5	Clock Rise and Fall Times	-	10	_	10	ns

^{*}These specifications represent an improvement over previously published specifications for the 8-, and 10-MHz MC68008 and are valid only for product bearing date codes of 8827 and later



NOTE: Timing measurements are referenced to and from a low voltage of 0.8 V and a high voltage of 2.0 V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall will be linear between 0.8 V and 2.0 V.

Figure 10-3. Clock Input Timing Diagram

10.10 AC ELECTRICAL SPECIFICATIONS — READ AND WRITE CYCLES

(VCC=5.0 VDC±5+; GND=0 V; $T_A=T_L$ to T_H ; (see Figures 10-4 and 10-5) (Applies To All Processors Except The MC68EC000)

Num	Characteristic	8 N	fHz*	10 1	VIHz*	12.5	MHz*		7 MHz 2F	16	MHz	20 N	ΛΗz ^ω	Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
6	Clock Low to Address Valid	_	62	_	50	_	50		50		30		25	ns
6A	Clock High to FC Valid		62	_	50	1	45	_	45	0	30	0	25	ns
7	Cłock High to Address, Data Bus High Impedance (Maximum)	_	80		70	_	60	_	50		50	_	42	ns
8	Clock High to Address, FC Invalid (Minimum)	0	_	0	_	,O	_	0	_	0	_	0		ns
91	Clock High to AS, DS Asserted	3	60	3	50	3	40	3	40	3	30	3	25	ns
112	Address Valid to AS, DS Asserted (Read)/AS Asserted (Write)	30	-	20	1	15	1	15	1	15	-	10		ns
11A ²	FC Valid to AS), DS Asserted (Read)/AS) Asserted (Write)	90		70	-	60	-	30	-	45	-	40	_	ns
12 ¹	Clock Low to AS, DS Negated		62		50	_	40	_	40	3	30	3	25	ns
13 ²	AS DS Negated to Address, FC Invalid	40	-	30	_	20		10	_	15	-	10		ns
14 ²	ASand DS Read) Width Asserted	270	_	195	_	160	-	120	_	120	_	100	_	ns
14A	DS Width Asserted (Write)	140		95		80		60		60	_	50		ns
15 ²	AS, DS Width Negated	150		105		65	_	60	—	60	_	50	_	ns
16	Clock High to Control Bus High Impedance	-	80	_	70	_	60	_	50	-	50	-	42	ns
17 ²	AS, DS Negated to R/W Invalid	40	_	30	_	20	_	10		15		10		ns
18 ¹	Clock High to R/W High (Read)	0	55	0	45	0	40	0	40	0	30	0	25	ns
20 ¹	Clock High to R/W Low (Write)	0	55	0	45	0	40	0	40	0	30	0	25	ns
20A ^{2,6}	AS Asserted to R/W Valid (Write)	_	10	-	10	_	10	1	10	-	10	_	10	ns
21 ²	Address Valid to R/W Low (Write)	20	_	0	_	0	_	0	_	0	_	0	_	ns
21A ²	FC Valid to R/W Low (Write)	60	_	50		30	_	20	_	30		25	_	ns
22 ²	R/W Low to DS Asserted (Write)	80	_	50	_	30	_	20	_	30	_	25	_	ns
23	Clock Low to Data-Out Valid (Write)	_	62	_	50	_	50	_	550	-	30	_	25	ns
25 ²	AS, DS) Negated to Data-Out Invalid (Write)	40 ¹ 0		30	_	20	_	15	_	15	_	10		ns

M68000 8-/16-/32-BIT MICROPROCESSORS USER'S MANUAL

Num	Characteristic	8 N	1Hz*	10 [ViHz*	12.5	MHz*	1	7 MHz 2F	16	MHz	20 M	/lHz**	Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
26 ²	Data-Out Valid to DS Asserted (Write)	40	_	30	_	20	_	15	_	15	_	10	_	ns
27 ⁵	Data-In Valid to Clock Low (Setup Time on Read)	10	_	10	_	10	_	7	_	5		5		ns
27A ⁵	Late BERR Asserted to Clock Low (setup Time)	45		45		45	_	-	_	_	_	_		ns
28 ²	AS, DS Negated to DTACK Negated (Asynchronous Hold)	0	240 ¹	0	190	0	150	0	110	0	110	0	95	ns
28A	AS, DS Negated to Data-In High Impedance	_	187	_	150	_	120	-	110	_	110	_	95	ns
29	AS, DS Negated to Data-In Invalid (Hold Time on Read)	0	-	0	_	0		0	_	0	_	0	_	ns
29A	AS, DS Negated to Data-In High Impedance	—	187	_	150	_	120	-	90	_	90	_	75	ns
30	AS, DS) Negated to BERR Negated	0	_	0	-	0	_	0	_	0	_	0	_	ns
31 ^{2,5}	DTACK Asserted to Data-In Valid (Setup Time)	_	90	_	65		50	_	40	-	50	_	42	ns
32	HALT) and RESET Input Transition Time	0	200	0	200	0	200	0	150	_	150	0	150	ns
33	Clock High to BG Asserted	_	62	_	50	_	40		40	0	30	0	25	ns
34	Clock High to BG Negated	_	62	_	50	_	40	_	40	0	30	0	25	ns
35	BR Asserted to BG Asserted	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
36 ⁷	BR Negated toBG Negated	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
37	BGACK Asserted to BG Negated	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
37A ⁸	BGACK Asserted to BR Negated	20	1.5 Clks	20	1.5 Clks	20	1.5 Clks	10	1.5 Clks	10	1.5 Clks	10	1.5 Clks	ns
38	BG Asserted to Control, Address, Data Bus High Impedance (AS Negated)	_	80	_	70	_	60	_	50		50	_	42	ns
39	BG Width Negated	1.5	_	1.5		1.5	_	1.5		1.5		1.5		clks
40	Clock Low to VMA Asserted	_	70	<u> </u>	70	_	70	_	50		50		40	ns
41	Clock Low to E Transition	_	55 ¹²	_	45		35		35		35		30	ns
42	E Output Rise and Fall Time	_	15	<u> </u>	15	_	15		15	_	15		12	ns
43	VMA Asserted to E High	200	_	150		90	_	80		80		60		ns
44	AS, DS Negated to VPA Negated	0	120	0	90	0	70	0	50	0	50	0	42	ns
45	E Low to Control, Address Bus Invalid (Address Hold Time)	30		10	_	10	_	10	_	10	_	10		ns
46	BGACK Width Low	1.5	_	1.5		1.5		1.5	l —	1.5		1.5	<u> </u>	ns

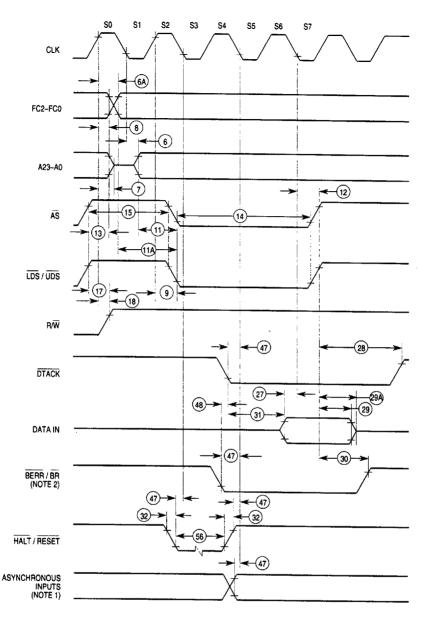
Num	Characteristic	8 N	lHz*	10 /	ViHz*	12.5	MHz*	1	7 MHz 2F	16	MHz	20 MHz**		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
47 ⁵	Asynchronous Input Setup Time	10	_	10	_	10	_	10	_	5	_	5	_	ns
48 ^{2,3}	BERR Asserted to DTACK Asserted	20	ı	20	İ	20	_	10		10		10		ns
48 ^{2,3,5}	DTACK Asserted to BERR Asserted (MC68010 Only)	1	80	_	55	-	35	-	-	1	_	_	_	ns
499	AS, DS, Negated to E Low	-70	70	-55	55	-45	45	-35	35	-35	35	-30	30	ns
50	E Width High	450	_	350		280	-	220	_	220	_	190		ns
51	E Width Low	700	_	550		440		340	_	340		290	-	ns
53	Data-Out Hold from Clock High	0	_	0	_	0	_	0	_	0	_	0		ns
54	E Low to Data-Out Invalid	30		20	_	15	_	10	_	10	-	5	_	ns
55	R/W Asserted to Data Bus Impedance Change	30	_	20	_	10	_	0	_	0	_	0	_	ns
56 ⁴	HALT (RESETPulse Width	10	_	10	_	10	_	10		10		10	_	clks
57	BGACK Negated to AS, DS, R/W Driven	1.5	_	1.5	_	1.5	_	1.5	_	1.5	_	1.5		clks
57A	BGACK Negated to FC, VMA Driven	1	_	1	_	1	_	1		1		1	_	clks
58 ⁷	BR Negated to AS, DS, RW Driven	1.5	_	1.5		1.5	-	1.5	_	1.5	_	1.5	-	clks
58A ⁷	BR Negated to FC, AS Driven	1	_	1	_	1	_	1	_	1	_	1	_	clks

^{*}These specifications represent improvement over previously published specifications for the 8-, 10-, and 12.5-MHz MC68000 and are valid only for product bearing date codes of 8827 and later.

NOTES:

- For a loading capacitance of less than or equal to 50 pF, subtract 5 ns from the value given in the maximum columns.
- 2. Actual value depends on clock period.
- If #47 is satisfied for both DTACK and BERR #48 may be ignored. In the absence of DTACK, BERR is an
 asynchronous input using the asynchronous input setup time (#47).
- 4. For power-up, the MC68000 must be held in the reset state for 100 ms to allow stabilization of on-chip circuitry. After the system is powered up, #56 refers to the minimum pulse width required to reset the processor.
- if the asynchronous input setup time (#47) requirement is satisfied for DTACK, the DTACK asserted to data setup time (#31) requirement can be ignored. The data must only satisfy the data-in to clock low setup time (#27) for the following clock cycle.
- 6. When AS and R/W are equally loaded (±20;pc), subtract 5 ns from the values given in these columns.
- The processor will negate BG and begin driving the bus again if external arbitration logic negates BR before asserting BGACK.
- The minimum value must be met to guarantee proper operation. If the maximum value is exceeded, BG may be reasserted.
- 9. The falling edge of S6 triggers both the negation of the strobes (AS and DS) and the falling edge of E. Either of these events can occur first, depending upon the loading on each signal. Specification #49 indicates the absolute maximum skew that will occur between the rising edge of the strobes and the falling edge of E.
- 10, 245 ns for the MC68008.
- 11. 50 ns for the MC68008
- 12. 50 ns for the MC68008.

^{**} This frequency applies only to MC68HC000 and MC68HC001.



NOTES:

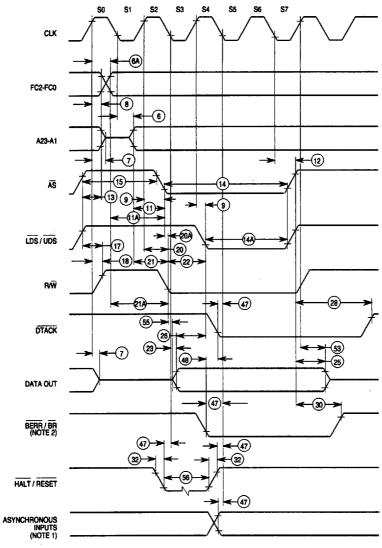
- Setup time for the asynchronous inputs IPL2-IPL0 and AVEC (#47) guarantees their recognition at the next falling edge of the clock.
- 2. BR need fall at this time only to insure being recognized at the end of the bus cycle.
- Timing measurements are referenced to and from a low voltage of 0.8 V and a high voltage of 2.0 V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall is linear between 0.8 V and 2.0 V.

Figure 10-4. Read Cycle Timing Diagram

(Applies To All Processors Except The MC68EC000)

MOTOROLA

M68000 8-/16-/32-BIT MICROPROCESSORS USER'S MANUAL



- NOTES:

 1. Timing measurements are referenced to and from a low voltage of 0.8 V and a high voltage of 2.0 V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall is linear between 0.8 V and 2.0 V.

 2. Because of loading variations, R/W may be valid after AS even though both are initiated by the rising edge of S2 (specification #20A).

Figure 10-5. Write Cycle Timing Diagram

(Applies To All Processors Except The MC68EC000)

10.11 AC ELECTRICAL SPECIFICATIONS—MC68000 TO M6800

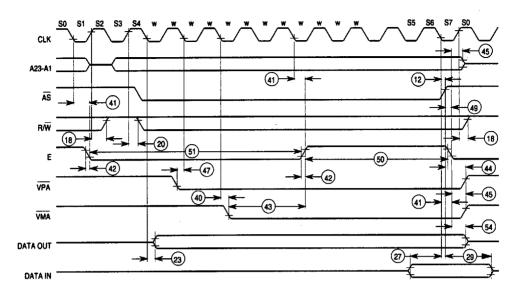
PERIPHERAL (V_{CC} = 5.0 Vdc ±5%; GND=0 Vdc; T_A = T_L TO T_H; refer to figures 10-6) (Applies To All Processors Except The MC68EC000)

Num	Characteristic	8 IV	¶Hz*	10 1	MHz*	12.5	MHz*		MHz 2F'	16	MHz	20 N	ЛНz"	Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
12 ¹	Clock Low to AS, DS Negated		62	-	50	-	40	_	40	3	30	3	25	ns
18 ¹	Clock High to R/W High (Read)	0	55	0	45	0	40	0	40	0	30	0	25	ns
20 ¹	Clock High to R/W Low (Write)	0	55	0	45	0	40	0	40	0	30	0	25	ns
23	Clock Low to Data-Out Valid (Write)		62	-	50	_	50	_	50	-	30	_	25	ns
27	Data-In Valid to Clock Low (Setup Time on Read)	10		10	_	10	_	7	_	5	_	5		ns
29	AS, DS Negated to Data-In Invalid (Hold Time on Read)	0	_	0	_	0		0	_	0		0	_	пѕ
40	Clock Low to VMA Asserted	_	70	_	70	_	70		50		50	_	40	ns
41	Clock Low to E Transition		55	_	45	_	35	_	35		35	_	30	ns
42	E Output Rise and Fall Time	_	15	_	15	-	15	_	15	_	15		12	ns
43	VMA Asserted to E High	200		150	_	90	_	80	_	80	_	60		ns
44	AS, DS Negated to VPA Negated	0	120	0	90	0	70	0	50	0	50	0	42	ns
45	E Low to Control, Address Bus Invalid (Address Hold Time)	30	_	10	_	10		10	_	10		10	_	ns
47	Asynchronous Input Setup Time	10	_	10	_	10	_	10	_	10		5		ns
492	AS, DS, Negated to E Low	-70	70	-55	55	-45	45	-35	35	-35	35	-30	30	ns
50	E Width High	450		350	_	280	_	220		220	_	190	_	ns
51	E Width Low	700	_	550	_	440	_	340		340		290	_	ns
54	E Low to Data-Out Invalid	30	_	20		15	_	10	_	10	_	5	<u> </u>	ns

^{*}These specifications represent improvement over previously published specifications for the 8-, 10-, and 12.5-MHz MC68000 and are valid only for product bearing date codes of 8827 and later.

- NOTES: 1. For a loading capacitance of less than or equal to 50 pF, subtract 5 ns from the value given in the maximum columns.
 - 2. The falling edge of S6 triggers both the negation of the strobes (\overline{AS} and \overline{DS}) and the falling edge of E. Either of these events can occur first, depending upon the loading on each signal. Specification #49 indicates the absolute maximum skew that will occur between the rising edge of the strobes and the falling edge of the E clock.

^{**} This frequency applies only to MC68HC000 and MC68HC001.



NOTE: This timing diagram is included for those who wish to design their own circuit to generate $\overline{\text{VMA}}$. It shows the best case possible attainable

Figure 10-6. MC68000 to M6800 Peripheral Timing Diagram (Best Case)
(Applies To All Processors Except The MC68EC000)

10.12 AC ELECTRICAL SPECIFICATIONS — BUS ARBITRATION (VCC=5.0

VDC±5%; GND=0 VDC, TA=TL TO TH; See Figure s 10-7 – 10-11) (Applies To All Processors Except The MC68EC000)

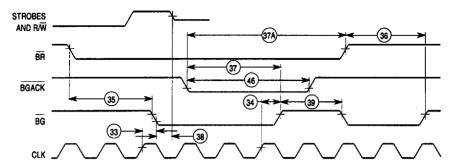
Num	Characteristic	8 MHz*		10 1	MHz*	12.5 MHz*		16.67 MHz 12F		16 MHz		20 MHz**		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
7	Clock High to Address, Data Bus High Impedance (Maximum)	-	80	_	70	_	60	_	50	_	50		42	ns
16	Clock High to Control Bus High Impedance	_	80		70	_	60	-	50		50	_	42	ns
33	Clock High to BG Asserted	-	62	_	50	_	40	0	40	0	30	0	25	ns
34	Clock High to BG Negated	_	62	_	50	_	40	0	40	0	30	0	25	ns
35	BR Asserted to BG Asserted	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
36 ¹	BR Negated to BG Negated	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
37	BGACK Asserted to BG Negated	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
37A ²	BGACK Asserted to BR Negated	20	1.5 Clks	20	1.5 Clks	20	1.5 Clks	10	1.5 Clks	10	1.5 Clks	10	1.5 Clks	Clks/
38	BG Asserted to Control, Address, Data Bus High Impedance (AS Negated)		80		70		60		50	_	50	_	42	ns
39	BG Width Negated	1.5	_	1.5	_	1.5	_	1.5	_	1.5		1.5		Clks
46	BGACK Width Low	1.5	_	1.5	_	1.5	-	1.5	_	1.5		1.5		Clks
47	Asynchronous Input Setup Time	10		10	_	10		5	_	5	_	5		ns
57	BGACK Negated to AS, DS, R/W Driven	1.5		1.5	_	1.5	_	1.5	_	1.5		1.5	_	Clks
57A	BGACK Negated to FC, VMA Driven	1	_	1	_	1	_	1	-	1	-	1	_	Ciks
58 ¹	BR Negated to AS, DS, R/W Driven	1.5	_	1.5	_	1.5	_	1.5	_	1.5		1.5	_	Clks
58A ¹	BR Negated to FC, VMA Driven	1	_	1		1	_	1	_	1	_	1	_	Clks

^{*}These specifications represent improvement over previously published specifications for the 8-, 10-, and 12.5-MHz MC68000 and are valid only for product bearing date codes of 8827 and later.

NOTES:

- Setup time for the synchronous inputs BGACK, IPLO-IPL2, and VPA guarantees their recognition at the next falling edge of the clock.
- 2. BR need fall at this time only in order to insure being recognized at the end of the bus cycle.
- 3. Timing measurements are referenced to and from a low voltage of 0.8 volt and a high voltage of 2.0 volts, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall will be lienar between 0.8 volt and 2.0 volts.
- The processor will negate BG and begin driving the bus again if external arbitration logic negates BR before
 asserting BGACK.
- The minimum value must be met to guarantee proper operation. If the maximum value is exceeded, BG may be reasserted.

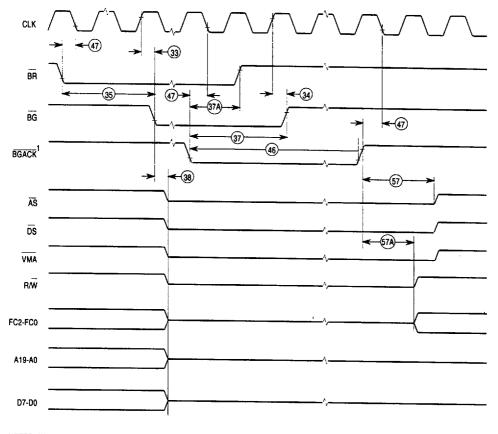
^{**} Applies only to the MC68HC000 and MC68HC001.



NOTE: Setup time to the clock (#47) for the asynchronous inputs BERR, BGACK, BR, DTACK, IPL2-IPL0, and VPA guarantees their recognition at the next falling edge of the clock.

Figure 10-7. Bus Arbitration Timing

(Applies To All Processors Except The MC68EC000)



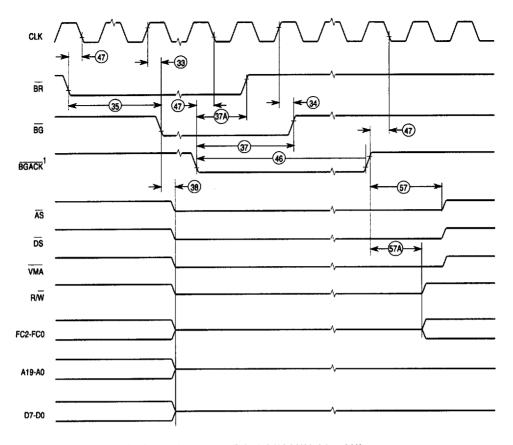
NOTES: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V. 1. MC68008 52-Pin Version only.

Figure 10-8. Bus Arbitration Timing (Applies To All Processors Except The MC68EC000)

MOTOROLA

M68000 8-/16-/32-BIT MICROPROCESSORS USER'S MANUAL

10-19

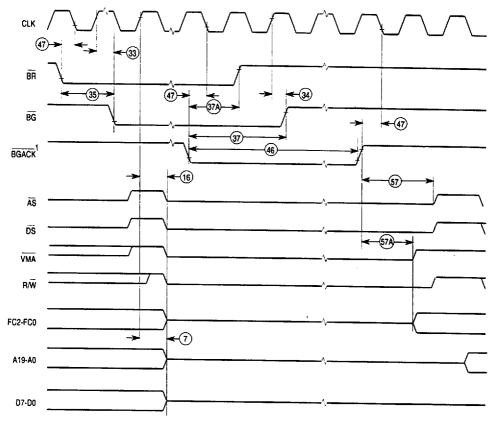


NOTES: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V.

1. MC68008 52-Pin Version only.

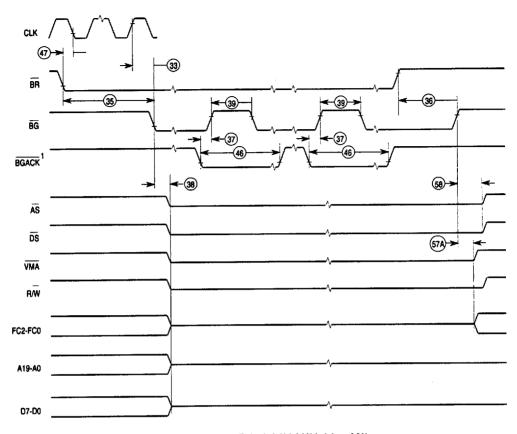
Figure 10-9. Bus Arbitration Timing — Idle Bus Case (Applies To All Processors Except The MC68EC000)

M68000 8-/16-/32-BIT MICROPROCESSORS USER'S MANUAL



NOTE: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V. 1 MC68008 52-Pin Version Only.

Figure 10-10. Bus Arbitration Timing — Active Bus Case (Applies To All Processors Except The MC68EC000)



NOTES: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V.

1. MC68008 52-Pin Version only.

Figure 10-11. Bus Arbitration Timing — Multiple Bus Request (Applies To All Processors Except The MC68EC000)

M68000 8-/16-/32-BIT MICROPROCESSORS USER'S MANUAL

10.13 MC68EC000 DC ELECTRICAL SPECIFICATIONS (VCC=5.0 VDC \pm 5;PC; GND=0 VDC; $T_A = T_L$ TO T_H)

	Characteristic	Symbol	Min	Max	Unit					
Input High Voltage		ViH	2.0	V _{CC}	V					
Input Low Voltage		VIL	GND-0.3	0.8	V					
Input Leakage Current @5.25 V	BERR, BR DTACK, CLK, IPL2-IPL0, AVEC MODE, HALT, RESET	lin	_	2.5 20	μΑ					
Three-State (Off State) Inp @2.4 V/0.4 V	A\$, A23-A0, D15-D0, FC2-FC0, \(\overline{LDS}\), R/\(\overline{W}\), \(\overline{UDS}\)	TSI		20	μА					
Output High Voltage (IOH=-400 μA)	AS, A23-A0, BG , D15-D0, FC2-FC0, LDS , R/W, UDS	∨он	VCC -0.75		٧					
Output Low Voltage (IOL = 1.6 mA) (IOL = 3.2 mA) (IOL = 5.0 mA) (IOL = 5.3 mA) Current Dissipation*	HALT A23-A0, BG, FC2-FC0 RESET AS, D15-D0, LDS, RW, UDS f=8 MHz	VOL	-	0.5 0.5 0.5 0.5	V mA					
	f=10 MHz f=12.5 MHz f=16.67 MHz f= 20 MHz	J.	-	30 35 50 70						
Power Dissipation	f=8 MHz f=10 MHz f=12.5 MHz f=16.67 MHz f=20 MHz	PD		0.13 0.16 0.19 0.26 0.38	W					
Capacitance (Vin=0 V, TA=	25°C, Frequency=1 MHz)**	0.00								
Load Capacitance	HALT All Others	CL	_	70 130	ρF					

^{*}Currents listed are with no loading.

^{**}Capacitance is periodically sampled rather than 100% tested.

10.14 MC68EC000 AC ELECTRICAL SPECIFICATIONS — READ AND WRITE CYCLES (VCC=5.0 VDC ± 5;PC; GND = 0 VDC; TA = TL TO TH; (See Figures

10-12 and 10-13)

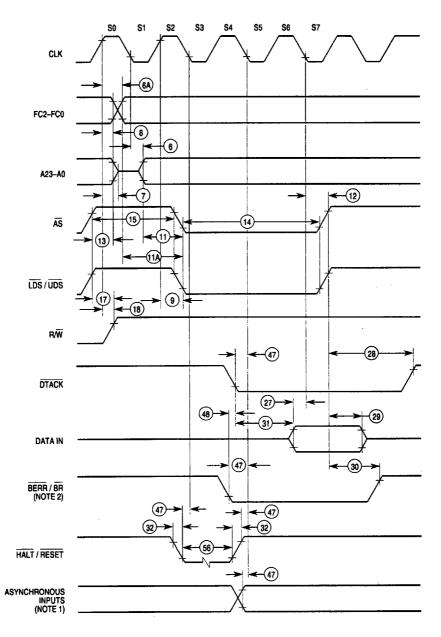
Num	Characteristic		AHz	10 N	ИНZ	12.5	MHz	16.67 MHz		20 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
6	Clock Low to Address Valid	_	35	_	35		35	_	30		25	ns
6A	Clock High to FC Valid		35	_	35	_	35	_	30	0	25	ns
7	Clock High to Address, Data Bus High Impedance (Maximum)	-	55	_	55		55	_	50	_	42	ns
8	Clock High to Address, FC Invalid (Minimum)	0	-	0		0	_	0		0		ns
91	Clock High to AS, DS Asserted	3	35	3	35	3	35	3	30	3	25	ns
112	Address Valid to AS, DS Asserted (Read)/AS Asserted (Write)	30	_	20.	_	15	_	15	_	10	-	ns
11A ²	FC Valid to AS, DS Asserted (Read)/ AS Asserted (Write)	45		45		45		45	_	40	_	ns
12 ¹	Clock Low to AS, DS Negated	3	35	3	35	3	35	3	30	3	25	ns
13 ²	AS, DS Negated to Address, FC Invalid	15		15	_	15		15	_	10		ns
14 ²	AS (and DS Read) Width Asserted	270	_	195	_	160	_	120	_	100	_	ns
14A ²	DS Width Asserted (Write)	140		95		80	<u> </u>	60		50		ns
15 ²	AS, DS Width Negated	150		105	_	65		60		50		ns
16	Clock High to Control Bus High Impedance	_	55	_	55	_	55	_	50	_	42	ns
172	AS, DS Negated to R/W Invalid	15	_	15		15		15	_	10		ns
18 ¹	Clock High to R/W High (Read)	0	35	0	35	0	35	0	30	0	25	ns
20 ¹	Clock High to R/W Low (Write)	0	35	0	35	0	35	0	30	0	25	ns
20A ^{2,6}	AS Asserted to R/W Low (Write)		10	<u> </u>	10		10		10		10	ns
212	Address Valid to R/W Low (Write)	0		0		0		0		0		ns
21A ²	FC Valid to R/W Low (Write)	60		50		30		30	<u> </u>	25		ns
222	R/W Low to DS Asserted (Write)	80		50		30		30		25	<u> </u>	ns
23	Clock Low to Data-Out Valid (Write)	_	35	_	35	_	35	_	30	_	25	ns
25 ²	AS, DS Negated to Data-Out Invalid (Write)	40		30	_	20	_	15	_	10	_	ns
26 ²	Data-Out Valid to DS Asserted (Write)	40		30	_	20		15	_	10	_	ns
27 ⁵	Data-In Valid to Clock Low (Setup Time on Read)	5	_	5	_	5	_	5	_	5		ns
28 ²	AS, DS Negated to DTACK Negated (Asynchronous Hold)	0	110	0	110	0	110	0	110	0	95	ns
28A	Clock High to DTACK Negated	0	110	0	110	0	110	0	110	0	95	ns

M68000 8-/16-/32-BIT MICROPROCESSORS USER'S MANUAL MOTOROLA

Num	n Characteristic		8 MHz		10 MHz		12.5 MHz		16.67 MHz		20 MHz	
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
29	AS, DS Negated to Data-In Invalid (Hold Time on Read)	0	_	0	_	0	_	0	_	0	_	ns
29A	AS, DS Negated to Data-In High Impedance	_	187		150	_	120	-	90		75	ns
30	AS, DS Negated to BERR Negated	0	_	0	-	0	_	0	-	0		ns
31 ² ,5	DTACK Asserted to Data-In Valid (Setup Time)	_	90		65	_	50	-	50	_	42	ns
32	HALT and RESET Input Transition Time	0	150	0	150	0	150	0	150	0	150	ns
33	Clock High to BG Asserted	_	35	_	35	_	35	0	30	0	25	ns
34	Clock High to BG Negated	_	35	_	35		35	0	30	0	25	ns
35	BR Asserted to BG Asserted	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
36 ⁷	BR Negated to BG Negated	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
38	BG Asserted to Control, Address, Data Bus High Impedance (AS Negated)	-	55	_	55	_	55	_	50	_	42	ns
39	BG Width Negated	1.5		1.5		1.5		1.5		1.5	_	Clks
44	AS, DS Negated to VPA Negated	0	55	0	55	0	55	0	50	0	42	ns
475	Asynchronous Input Setup Time	5	_	5	_	5	_	5	_	5	_	ns
48 ² ,3	BERH Asserted to DTACK Asserted	20	_	20	_	20	_	10		10	_	ns
53	Data-Out Hold from Clock High	0		0	_	0		0	_	0		ns
55	R/W Asserted to Data Bus Impedance Change	30		20	_	10	_	0	_	0		ns
56 ⁴	HALT/RESET Pulse Width	10		10		10	_	10	_	10		Clks
58 ⁷	BR Negated to AS, DS, R/W Driven	1.5		1.5		1.5	_	1.5	_	1.5	_	Clks
58A ⁷	BR Negated to FC, VMA Driven	1	_	1		1	_	1	_	1	_	Clks

NOTES:1. For a loading capacitance of less than or equal to 50 pF, subtract 5 ns from the value given in the maximum columns.

- 2. Actual value depends on clock period.
- 3.If #47 is satisfied for both DTACK and BERR #48 may be ignored. In the absence of DTACK, BERR is an asynchronous input using the asynchronous input setup time (#47).
- 4. For power-up, the MC68EC000 must be held in the reset state for 520 clocks to allow stabilization of onchip circuitry. After the system is powered up, #56 refers to the minimum pulse width required to reset the processor.
- 5. If the asynchronous input setup time (#47) requirement is satisfied for DTACK, the DTACK-asserted to data setup time (#31) requirement can be ignored. The data must only satisfy the data-in to clock low setup time (#27) for the following clock cycle.
- 6. When \overline{AS} and R/\overline{W} are equally loaded (±20;pc), subtract 5 ns from the values given in these columns.
- The minimum value must be met to guarantee proper operation. If the maximum value is exceeded, BG may be reasserted.
- 8. DS is used in this specification to indicate UDS and LDS.

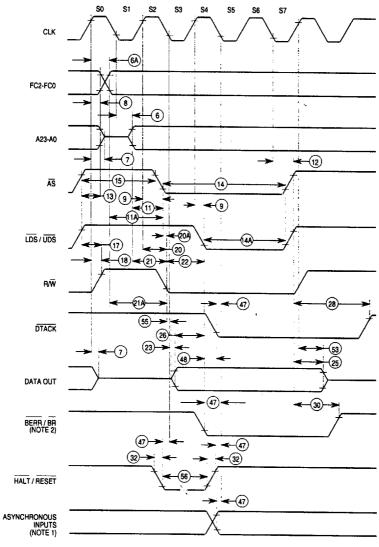


NOTES:

- Setup time for the asynchronous inputs IPL2-IPL0 and AVEC (#47) guarantees their recognition at the next falling edge of the clock.
- 2. BR need fall at this time only to insure being recognized at the end of the bus cycle.
- Timing measurements are referenced to and from a low voltage of 0.8 V and a high voltage of 2.0 V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall is linear between 0.8 V and 2.0 V.

Figure 10-12. MC68EC000 Read Cycle Timing Diagram

M68000 8-/16-/32-BIT MICROPROCESSORS USER'S MANUAL



NOTES:

- Timing measurements are referenced to and from a low voltage of 0.8 V and a high voltage of 2.0 V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall is linear between 0.8 V and 2.0 V.
- Because of loading variations, R/W may be valid after AS even though both are initiated by the rising edge of S2 (specification #20A).

Figure 10-13. MC68EC000 Write Cycle Timing Diagram

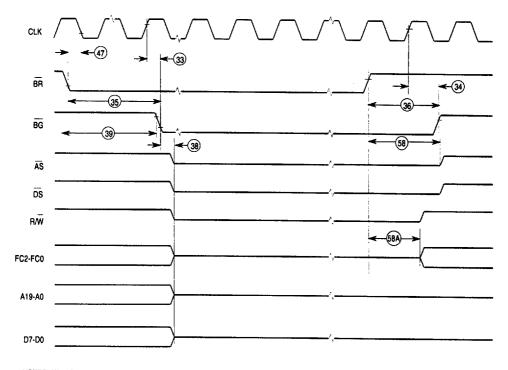
10.15 MC68EC000 AC ELECTRICAL SPECIFICATIONS—BUS

ARBITRATION (VCC=5.0VDC ± 5%; GND=0 VDC; TA = TL TO TH; see Figure 10-14)

Num	Characteristic	8 M	AHz	10	MHz	12.5	MHz	16.67	7 MHz	20	MHz	Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
7	Clock High to Address, Data Bus High Impedance (Maximum)	-	55	_	55	_	55	-	50	_	42	ns
16	Clock High to Control Bus High Impedance	1	55	_	55	_	55	-	50	_	42	ns
33	Clock High to BG Asserted	_	35		35	_	35	0	30	0	25	ns
34	Clock High to BG Negated		35	1	35	_	35	0	30	0	25	ns
35	BR Asserted to BG Asserted	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
36 ⁷	BR Negated to BG Negated	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	1.5	3.5	Clks
38	BG Asserted to Control, Address, Data Bus High Impedance (AS Negated)		55	-	55	. —	55		50	_	42	ns
39	BG Width Negated	1.5	_	1.5	_	1.5	_	1.5	_	1.5	_	Ciks
47	Asynchronous Input Setup Time	5	_	5	_	5	_	5	_	5		ns
58 ¹	BR Negated to AS, DS, R/W Driven	1.5	_	1.5	_	1.5	_	1.5	_	1.5		Clks
58A ¹	BR Negated to FC Driven	1	_	1	_	1	_	1	_	1	_	Clks

NOTES: 1.The minimum value must be met to guarantee proper operation. If the maximum value is exceeded, BG may be reasserted.

2.DS is used in this specification to indicate UDS and LDS.



NOTES: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V.

Figure 10-14. MC68EC000 Bus Arbitration Timing Diagram